

## 74LVQ273 Low Voltage Octal D-Type Flip-Flop

### General Description

The LVQ273 has eight edge-triggered D-type flip-flops with individual D inputs and Q outputs. The common buffered Clock (CP) and Master Reset ( $\overline{MR}$ ) input load and reset (clear) all flip-flops simultaneously.

The register is fully edge-triggered. The state of each D input, one setup time before the LOW-to-HIGH clock transition, is transferred to the corresponding flip-flop's Q output. All outputs will be forced LOW independently of Clock or Data inputs by a LOW voltage level on the  $\overline{MR}$  input. The device is useful for applications where the true output only is required and the Clock and Master Reset are common to all storage elements.

### Features

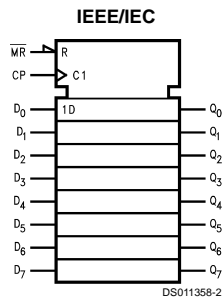
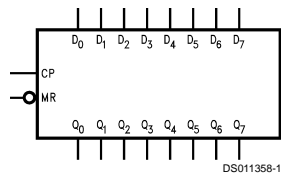
- Ideal for low power/low noise 3.3V applications
- Implements patented EMI reduction circuitry
- Available in SOIC JEDEC, SOIC EIAJ and QSOP packages
- Guaranteed simultaneous switching noise level and dynamic threshold performance
- Improved latch-up immunity
- Guaranteed incident wave switching into 75Ω
- 4 kV minimum ESD immunity

### Ordering Code:

Order Number	Package Number	Package Description
74LVQ273SC	M20B	20-Lead (0.300" Wide) Molded Small Outline Package, SOIC JEDEC
74LVQ273SJ	M20D	20-Lead Shrink Molded Small Outline Package, SOIC EIAJ
74LVQ273QSC	MQA20	20-Lead (0.150" Wide) Molded Shrink Small Outline Package, SSOP JEDEC

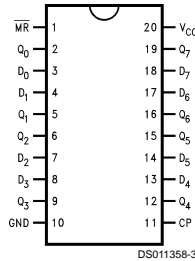
Devices also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering code.

### Logic Symbol



### Connection Diagram

Pin Assignment for SOIC and QSOP



### Pin Descriptions

Pin Names	Description
D <sub>0</sub> -D <sub>7</sub>	Data Inputs
$\overline{MR}$	Master Reset
CP	Clock Pulse Input
Q <sub>0</sub> -Q <sub>7</sub>	Data Outputs

### Absolute Maximum Ratings (Note 1)

Supply Voltage ( $V_{CC}$ )	-0.5V to +7.0V
DC Input Diode Current ( $I_{IK}$ )	
$V_I = -0.5V$	-20 mA
$V_I = V_{CC} + 0.5V$	+20 mA
DC Input Voltage ( $V_I$ )	-0.5V to $V_{CC} + 0.5V$
DC Output Diode Current ( $I_{OK}$ )	
$V_O = -0.5V$	-20 mA
$V_O = V_{CC} + 0.5V$	+20 mA
DC Output Voltage ( $V_O$ )	-0.5V to $V_{CC} + 0.5V$
DC Output Source	
or Sink Current ( $I_O$ )	$\pm 50$ mA
DC $V_{CC}$ or Ground Current	
( $I_{CC}$ or $I_{GND}$ )	$\pm 400$ mA
Storage Temperature ( $T_{STG}$ )	-65°C to +150°C
DC Latch-up Source or	
Sink Current	$\pm 300$ mA

### Recommended Operating Conditions (Note 2)

Supply Voltage ( $V_{CC}$ )	2.0V to 3.6V
Input Voltage ( $V_I$ )	0V to $V_{CC}$
Output Voltage ( $V_O$ )	0V to $V_{CC}$
Operating Temperature ( $T_A$ )	-40°C to +85°C
Minimum Input Edge Rate $\Delta V/\Delta t$	
$V_{IN}$ from 0.8V to 2.0V	
$V_{CC}$ @ 3.0V	125 mV/ns

**Note 1:** The "Absolute Maximum Ratings" are those values beyond which the safety of the device cannot be guaranteed. The device should not be operated at these limits. The parametric values defined in the Electrical Characteristics tables are not guaranteed at the absolute maximum ratings. The "Recommended Operating Conditions" table will define the conditions for actual device operation.

**Note 2:** Unused inputs must be held HIGH or LOW. They may not float.

### DC Electrical Characteristics

Symbol	Parameter	$V_{CC}$ (V)	$T_A = +25^\circ\text{C}$		$T_A = -40^\circ\text{C to } +85^\circ\text{C}$	Units	Conditions
			Typ	Guaranteed Limits			
$V_{IH}$	Minimum High Level Input Voltage	3.0	1.5	2.0	2.0	V	$V_{OUT} = 0.1V$ or $V_{CC} - 0.1V$
$V_{IL}$	Maximum Low Level Input Voltage	3.0	1.5	0.8	0.8	V	$V_{OUT} = 0.1V$ or $V_{CC} - 0.1V$
$V_{OH}$	Minimum High Level Output Voltage	3.0	2.99	2.9	2.9	V	$I_{OUT} = -50 \mu\text{A}$
		3.0		2.58	2.48	V	$V_{IN} = V_{IL}$ or $V_{IH}$ (Note 3) $I_{OH} = -12 \text{ mA}$
$V_{OL}$	Maximum Low Level Output Voltage	3.0	0.002	0.1	0.1	V	$I_{OUT} = 50 \mu\text{A}$
		3.0		0.36	0.44	V	$V_{IN} = V_{IL}$ or $V_{IH}$ (Note 3) $I_{OL} = 12 \text{ mA}$
$I_{IN}$	Maximum Input Leakage Current	3.6		$\pm 0.1$	$\pm 1.0$	$\mu\text{A}$	$V_I = V_{CC}, \text{ GND}$
$I_{OLD}$	Minimum Dynamic	3.6			36	mA	$V_{OLD} = 0.8V$ Max (Note 5)
$I_{OHD}$	Output Current (Note 4)	3.6			-25	mA	$V_{OHD} = 2.0V$ Min (Note 5)
$I_{CC}$	Maximum Quiescent Supply Current	3.6		4.0	40.0	$\mu\text{A}$	$V_{IN} = V_{CC}$ or GND
$V_{OLP}$	Quiet Output Maximum Dynamic $V_{OL}$	3.3	0.4	0.8		V	(Notes 6, 7)
$V_{OLV}$	Quiet Output Minimum Dynamic $V_{OL}$	3.3	-0.3	-0.8		V	(Notes 6, 7)
$V_{IHD}$	Maximum High Level Dynamic Input Voltage	3.3	1.7	2.0		V	(Notes 6, 8)
$V_{ILD}$	Maximum Low Level Dynamic Input Voltage	3.3	1.6	0.8		V	(Notes 6, 8)

**Note 3:** All outputs loaded; thresholds on input associated with output under test.

**Note 4:** Maximum test duration 2.0 ms, one output loaded at a time.

**Note 5:** Incident wave switching on transmission lines with impedances as low as 75Ω for commercial temperature range is guaranteed for.

**Note 6:** Worst case package.

**Note 7:** Max number of outputs defined as (n). Data Inputs are driven 0V to 3.3V; one output at GND.

**Note 8:** Max number of Data Inputs (n) switching. (n - 1) inputs switching 0V to 3.3V. Input-under-test switching: 3.3V to threshold ( $V_{ILD}$ ), 0V to threshold ( $V_{IHD}$ ), f = 1 MHz.

## AC Electrical Characteristics

Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> = +25°C			T <sub>A</sub> = -40°C to +85°C		Units
			C <sub>L</sub> = 50 pF			C <sub>L</sub> = 50 pF		
			Min	Typ	Max	Min	Max	
f <sub>max</sub>	Maximum Clock Frequency	2.7 3.3 ±0.3	50 90			45 75		MHz
t <sub>PLH</sub>	Propagation Delay CP to Q <sub>n</sub>	2.7 3.3 ±0.3	4.0 4.0	9.6 8.0	17.6 12.5	3.0 3.0	20.0 14.0	ns
t <sub>PHL</sub>	Propagation Delay CP to Q <sub>n</sub>	2.7 3.3 ±0.3	4.0 4.0	10.2 8.5	18.3 13.0	3.5 3.5	20.5 14.5	ns
t <sub>PHL</sub>	Propagation Delay $\overline{MR}$ to Q <sub>n</sub>	2.7 3.3 ±0.3	4.0 4.0	10.2 8.5	18.3 13.0	3.5 3.5	20.0 14.0	ns
t <sub>OSSL</sub>	Output to Output Skew (Note 9)	2.7 3.3 ±0.3		1.0 1.0	1.5 1.5		1.5 1.5	ns

**Note 9:** Skew is defined as the absolute value of the difference between the actual propagation delay for any two outputs within the same packaged device. The specification applies to any outputs switching in the same direction, either HIGH to LOW (t<sub>OSSL</sub>) or LOW to HIGH (t<sub>OSLH</sub>). Parameter guaranteed by design. Not tested.

## AC Operating Requirements

Symbol	Parameter	V <sub>CC</sub> (V)	T <sub>A</sub> = +25°C		T <sub>A</sub> = -40°C to +85°C		Units
			C <sub>L</sub> = 50 pF		C <sub>L</sub> = 50 pF		
			Typ	Guaranteed Minimum			
t <sub>s</sub>	Setup Time, HIGH or LOW D <sub>n</sub> to CP	2.7 3.3 ±0.3		6.5 5.0	8.5 6.0		ns
t <sub>H</sub>	Hold Time, HIGH or LOW D <sub>n</sub> to CP	2.7 3.3 ±0.3		0.0 0.0	0.0 0.0		ns
t <sub>w</sub>	Clock Pulse Width HIGH or LOW	2.7 3.3 ±0.3		7.0 5.5	8.5 6.0		ns
t <sub>w</sub>	$\overline{MR}$ Pulse Width HIGH or LOW	2.7 3.3 ±0.3		7.0 5.5	8.5 6.0		ns
t <sub>w</sub>	Recovery Time $\overline{MR}$ to CP	2.7 3.3 ±0.3		5.0 4.0	6.5 4.5		ns

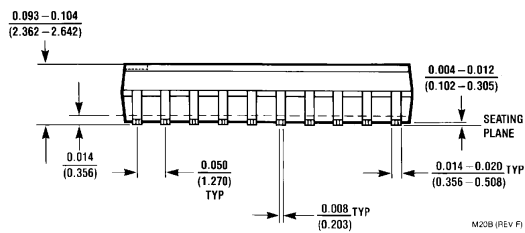
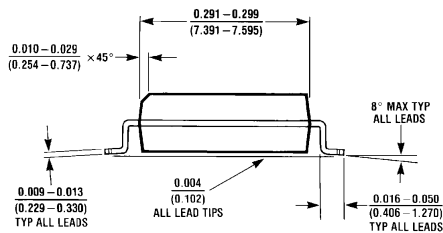
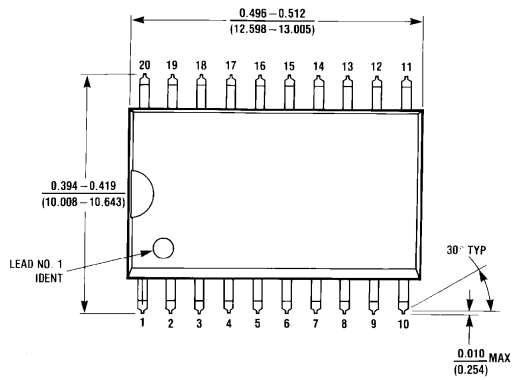
## Capacitance

Symbol	Parameter	Typ	Units	Conditions
C <sub>IN</sub>	Input Capacitance	4.5	pF	V <sub>CC</sub> = Open
C <sub>PD</sub> (Note 10)	Power Dissipation Capacitance	35	pF	V <sub>CC</sub> = 3.3V

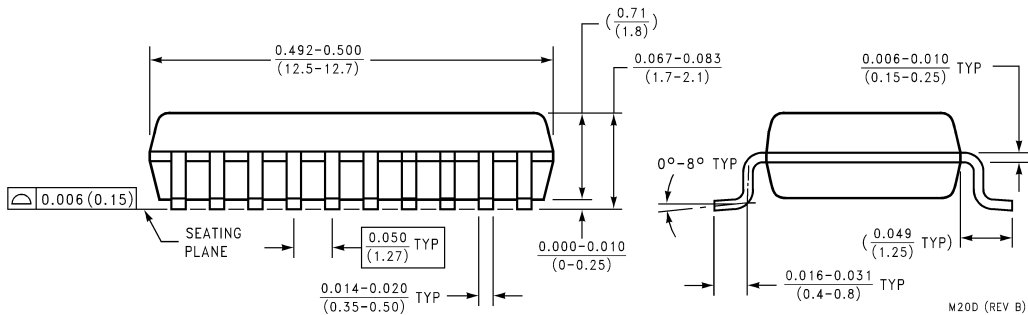
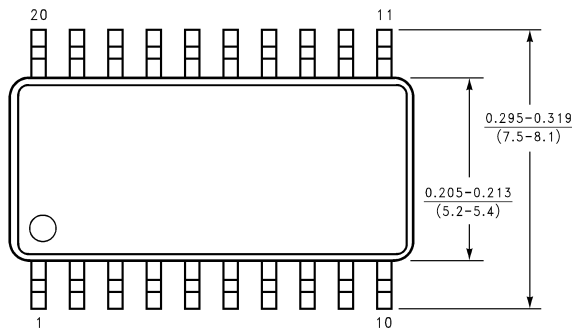
**Note 10:** C<sub>PD</sub> is measured at 10 MHz.



**Physical Dimensions** inches (millimeters) unless otherwise noted

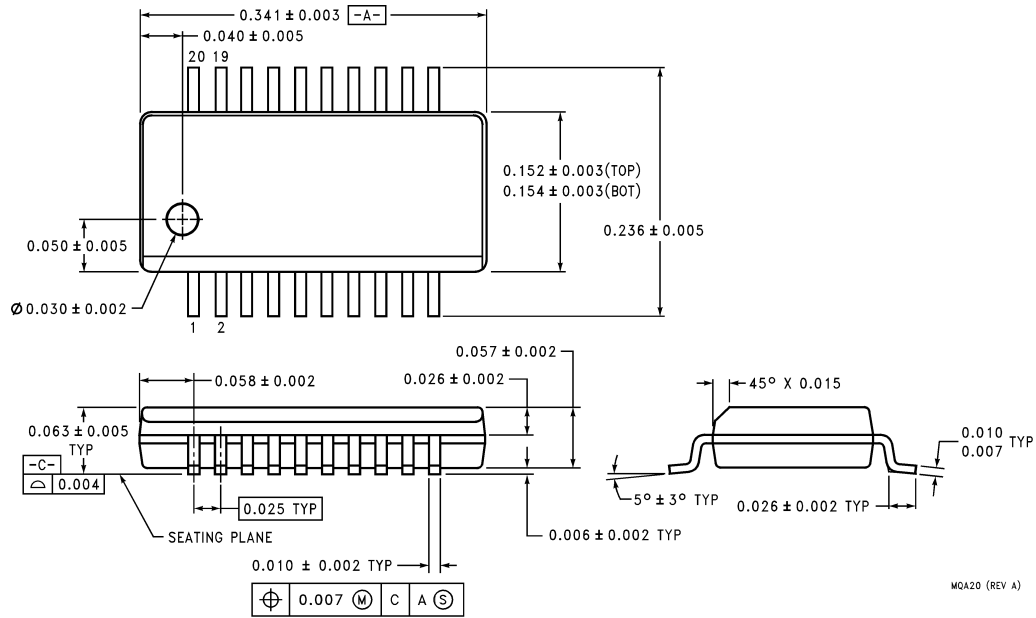


**20-Lead (0.300" Wide) Molded Small Outline Package, SOIC JEDEC**  
**Package Number M20B**



**20-Lead Shrink Molded Small Outline Package, SOIC EIAJ**  
**Package Number M20D**

**Physical Dimensions** inches (millimeters) unless otherwise noted (Continued)



**20-Lead (0.150" Wide) Molded Shrink Small Outline Package, SSOP JEDEC  
(also known as QSOP)  
Package Number MQA20**

MQA20 (REV A)

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